

Figure 1. XPS chemical components of (a) HF cleaned Si and (b) degreased SiON at each experimental step of MoF₆ and Si₂H₆ saturation doses at 120°C. MoF₆ and Si₂H₆ showed self-limiting behavior on HF cleaned Si. Degreased SiON showed inherent non-reactivity for both MoF₆ and Si₂H₆. XPS peaks of (c) Si 2p and (d) Mo 3d after a MoF₆ saturation dose and 1 pulse of Si₂H₆ on HF cleaned Si. One saturation cycle of MoF₆ and Si₂H₆ showed the Mo 3d peak position at 227.4 eV which was consistent with a monolayer of MoSi₂ formation.





Figure 2. Selective deposition of $MoSi_x$ on a patterned sample and additional incorporation of Si from extra Si_2H_6 pulse. (a) As loaded HF cleaned Si, SiO_2 and patterned sample. (b) Selective deposition of sub-stoichiometric $MoSi_x$ on Si and Si portion of a patterned sample. (c) Additonal Si into $MoSi_x$ film by pulsing Si_2H_6 . Figure 3. Surface morphology of Si (a) after MoSi_x ALD, (b) after the 500°C anneal for 3 mins, and (c) after the 900°C spike anneal. The surfaces were smooth and atomically flat. (d) SiO₂ surface was clean with a few MoSi_x nuclei.



Figure 4. Depth profile XPS coupled with Ar^+ sputtering. The bulk of $MoSi_x$ film was Si abundant (x=1.4) with <10% O and F. O increased closer to the substrate showing the interfacial oxide layer between the $MoSi_x$ film and Si substrate.



Figure 5. Cross-sectional TEM image of the patterned samples after the selective $MoSi_x$ deposition. (a) $MoSi_x$ was selectively deposited on Si after the 5 ALD cycles followed by additional Si from Si_2H_6 . Plane structured SiO_2 and Si_3N_4 were inherently non-reactive to $MoSi_x$ ALD. (b) Selective deposition of $MoSi_x$ was also achieved on 3D nanostructured Si over SiO_2 .